

Patent Application
Docket No.27889-37

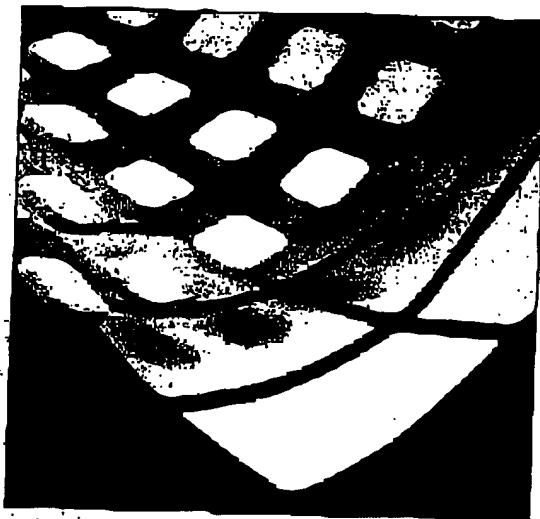
Exhibit A

Advertisements for "thermal interface materials"

1. W.L. Gore and Associates, Inc.'s POLARCHIP™
2. Thermalloy, Inc.'s Thermalcote II
3. Stockwell Rubber Company's Thermal Management Components

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Gore's POLARCHIP™ Thermal Interface Materials... Bridge the Gap Between Hot PCBs and Cool Heat Sinks.



POLARCHIP Thermal Interface Materials are fluoropolymer composites that consist of an ePTFE matrix filled with Boron Nitride particles. They are...

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- Soft, Conformable and Compliant
- Robust, Durable, Easy to Handle, Use and Install

POLARCHIP Materials are An Ideal "Gap-Filler" for Large or Variable Gaps

Innovative Solutions. Defining Technology...



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Thermalcote II
Non-Silicone Thermal Joint Compound

Thermalloy Inc.

10000 Highway 105, Suite 100, Dallas, TX 75243-1000

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Reader Interest Rating

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Low	Reader Inquiry No. 86

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